

ABSTRACT

The present invention teaches the deposition of a pattern of interconnecting lines and bond pads. Passivation layers are deposited over this metal pattern. A layer of photosensitive polyimide is deposited over the passivation layers. This layer of photosensitive polyimide is patterned, exposed and developed to expose the underlying bonding pads. The remaining polyimide is cured and cross-linked and remains in place to serve as a buffer during further device packaging. Key to the present invention is that the remaining photosensitive polyimide is not removed after the bond pad has been exposed.